

# Hyperfast Soft Recovery Diode, 30 A FRED Pt<sup>®</sup> Gen 4



PRIMARY CHARACTERISTICS						
I <sub>F(AV)</sub>	30 A					
$V_{R}$	600 V					
V <sub>F</sub> at I <sub>F</sub>	1.37 V					
t <sub>rr</sub> typ.	see Recovery table					
T <sub>J</sub> max.	175 °C					
Package	TO-247AD 2L					
Circuit configuration	Single					

#### **FEATURES**







Polymide passivated chip for high reliability standard



- 175 °C operating junction temperature
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

#### **DESCRIPTION**

Gen 4 Fred technology, state of the art, ultrafast  $V_F$ , soft switching optimized for Discontinuous (Critical) Mode (DCM) and IGBT F/W diode.

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Cathode to anode voltage	$V_R$		600	V			
Average rectified current	I <sub>F(AV)</sub>	T <sub>C</sub> = 122 °C	30	^			
Single pulse forward current	I <sub>FSM</sub>	$T_C = 25$ °C, $t_p = 8.3$ ms half sine wave	240	A			
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C			

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS MIN		TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_{R}$	$I_R = 100 \mu A$	600	-	-		
Forward voltage		$I_F = 30 \text{ A}$	-	1.65	2	V	
	V <sub>F</sub>	I <sub>F</sub> = 60 A	-	1.95	-		
		I <sub>F</sub> = 30 A, T <sub>J</sub> = 125 °C	-	1.44	-		
		I <sub>F</sub> = 60 A, T <sub>J</sub> = 125 °C	-	1.78	-		
		I <sub>F</sub> = 30 A, T <sub>J</sub> = 150 °C	-	1.37	1.6		
		I <sub>F</sub> = 60 A, T <sub>J</sub> = 150 °C	-	1.68	-		
Reverse leakage current	I <sub>R</sub>	$V_R = V_R$ rated	-	-	50		
		T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	-	500	μΑ	
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 600 V	-	18.3	-	pF	



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL TEST CONDITIONS MIN. TYP. MAX.						UNITS	
Poverse receivery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 30 A dI <sub>F</sub> /dt = 1000 A/μs V <sub>R</sub> = 400 V	-	55	-	ns	
Reverse recovery time		T <sub>J</sub> = 125 °C		-	75	-		
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	13	-	A	
		T <sub>J</sub> = 125 °C		-	23	-		
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	500	-	nC	
		T <sub>J</sub> = 125 °C		-	1250	-		

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Thermal resistance, junction to case	R <sub>thJC</sub>		1	-	1		
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	°C/W	
Thermal resistance, case to heat sink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	ı	0.4	-		
Weight			1	6.0	-	g	
Weight			1	0.21	-	oz.	
Mounting torque			6.0 (5)	-	12 (20)	kgf · cm (lbf · in)	
Marking device		Case style TO-247AD 2L	E4PH3006L				

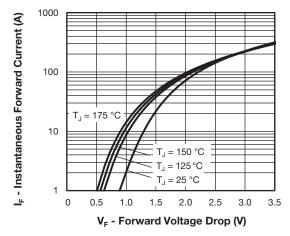


Fig. 1 - Typical Forward Voltage Drop Characteristics

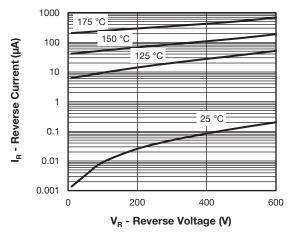


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

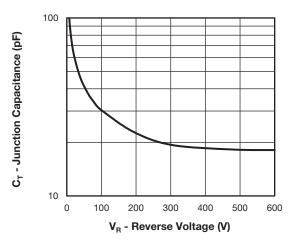


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

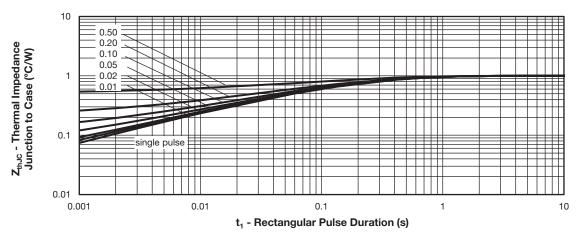


Fig. 4 - Max. Thermal Impedance Z<sub>thJC</sub> Characteristics

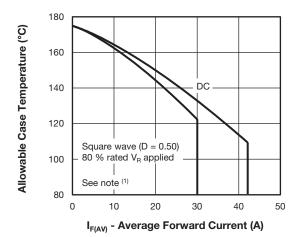


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

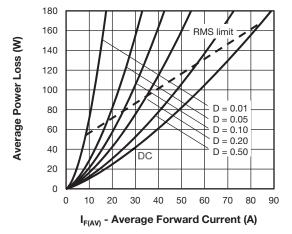


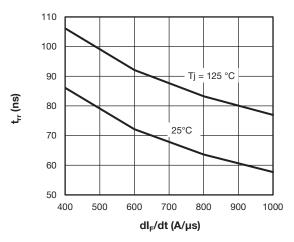
Fig. 6 - Forward Power Loss Characteristics

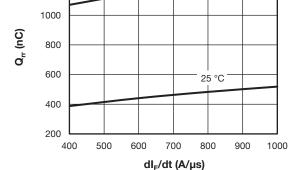
#### Note

<sup>(1)</sup> Formula used:  $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$ ;  $Pd = forward power loss = I_{F(AV)} \times V_{FM} at (I_{F(AV)}/D)$  (see fig. 5);  $Pd_{REV} = inverse power loss = V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = rated V_R$ 

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# Vishay Semiconductors





125 °C

1400

1200

Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

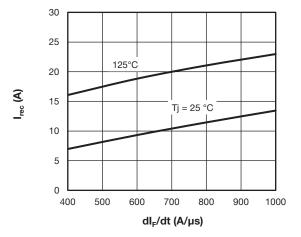
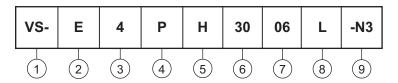


Fig. 9 - Typical Reverse Current vs. dl<sub>F</sub>/dt



#### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

2 - Circuit configuration:

E = single diode, 2 pins

3 - FRED Pt Gen 4

4 - P = TO-247 package

5 - Process type:

H = hyperfast recovery

6 - Current rating (30 = 30 A)

7 - Voltage rating (06 = 600 V)

8 - L = long lead

9 - Environmental digit:

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-E4PH3006L-N3	25	500	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95536				
Part marking information	www.vishay.com/doc?95648				

### **TO-247AD 2L**

#### **DIMENSIONS** in millimeters and inches



View B

SYMBOL	MILLIN	IETERS	INC	NOTES	
STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4
D2	0.51	1.35	0.020	0.053	

Section C - C, D - D

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Е	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46	BSC	0.215	BSC	
ØK	0.2	254	0.0	0.010	
L	19.81	20.32	0.780	0.800	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217	'BSC	
		•		•	

#### **Notes**

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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